

GB200-Class Copper Liquid Cold Plate

Key Specifications & Performance Summary

Part No.: TC-BZP-GB200-01A

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Revision: A

OVERVIEW

- Batch-validated solution for high-power AI server liquid cooling
- Platform: GB200-class
- Material: T2 copper
- Welding process: nitrogen protection brazing + laser welding
- Working condition: 25 +/- 2 deg C, 2.5 L/min, pure water
- Suitable for GPU liquid cooling, coolant compatibility testing, and liquid cooling evaluation



Core Specifications		Performance Parameters	
Heat dissipation	1200 W + 1200 W + 300 W	Working condition	Feed liquid temperature 25 +/- 2 deg C
Material	T2 copper	Coolant	Pure water
Welding process	Nitrogen protection brazing, laser welding	Flow rate	2.5 L/min
Pressure	0.6 MPa	Flow resistance	35 +/- 5 kPa
Dimensions	235 mm x 190 mm x 30 mm	Cold plate surface temperature	Below 43 deg C

Engineering Positioning	Available Support Documents
GB200-class copper liquid cold plate for high-power AI server GPU thermal evaluation. Suitable for sample testing, coolant compatibility review, pressure drop evaluation, and liquid cooling reliability studies.	Basic dimensional information, material information, pressure drop data, leak test records, pressure holding test records, and sample quotation can be provided according to project requirements.

Note: This datasheet is for GB200-class liquid cooling board evaluation. Final configuration, fittings, surface treatment, and test documentation shall be confirmed according to sample order requirements.